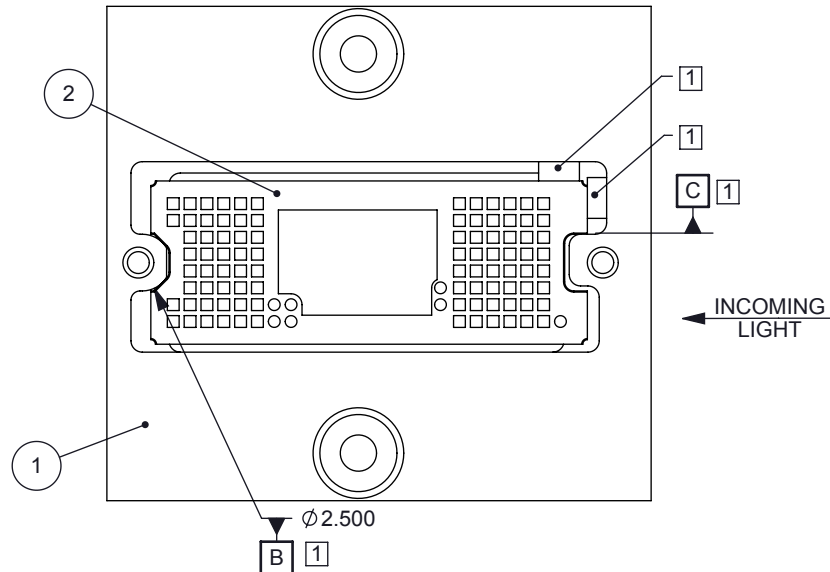


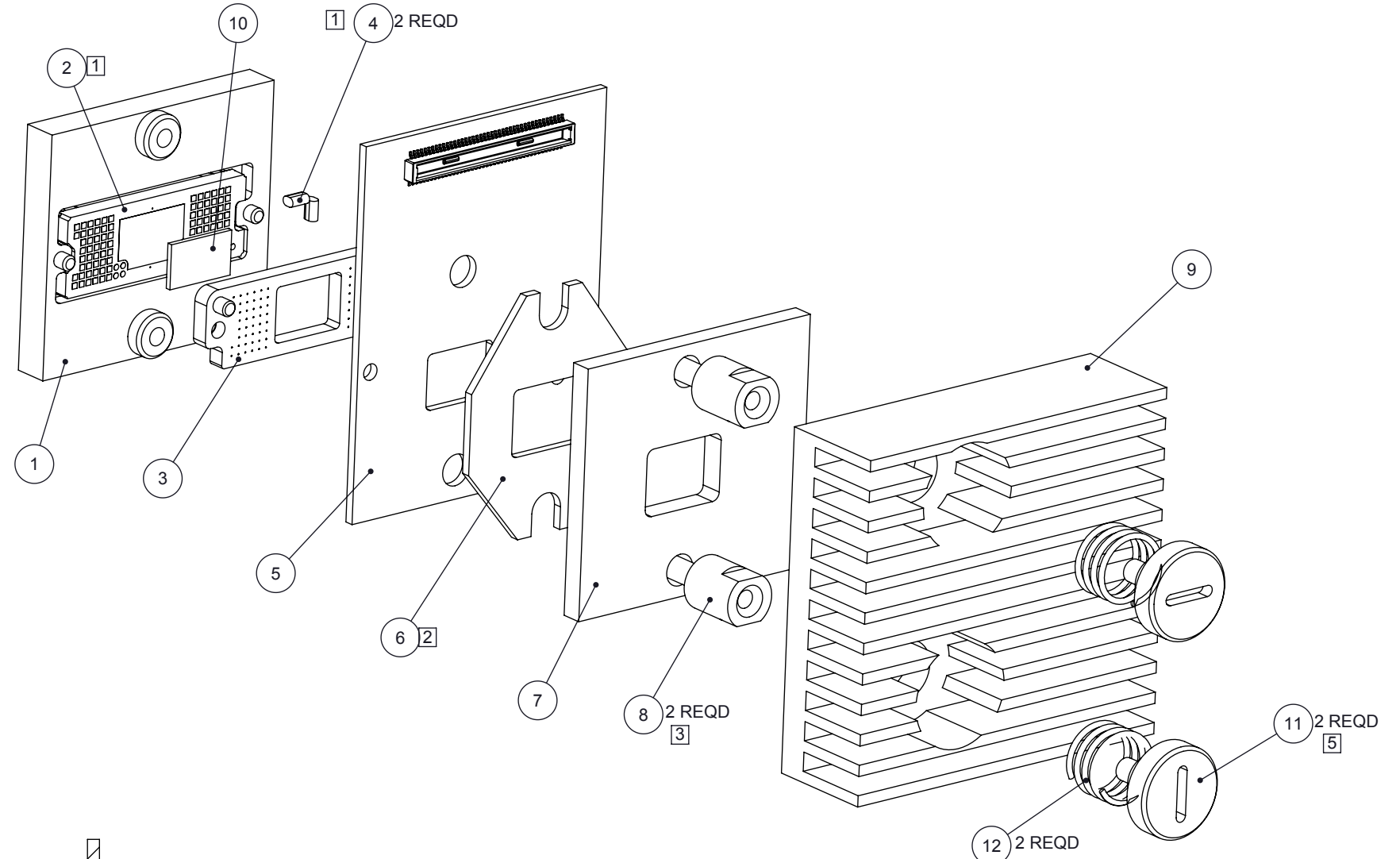
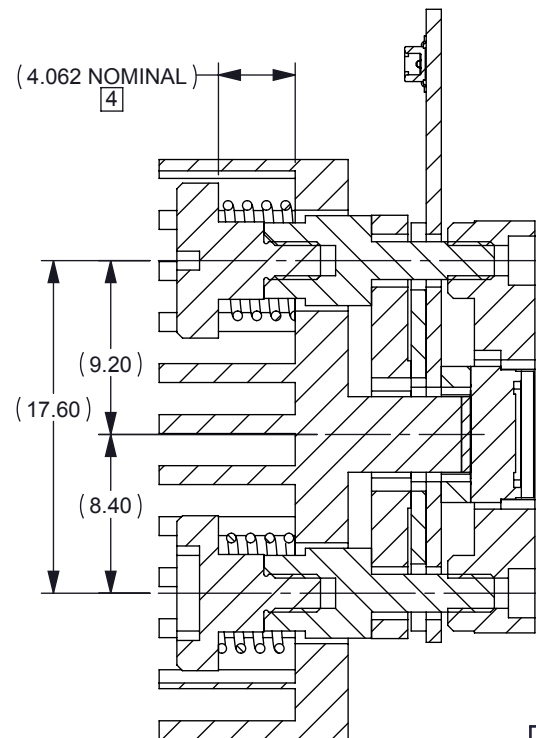
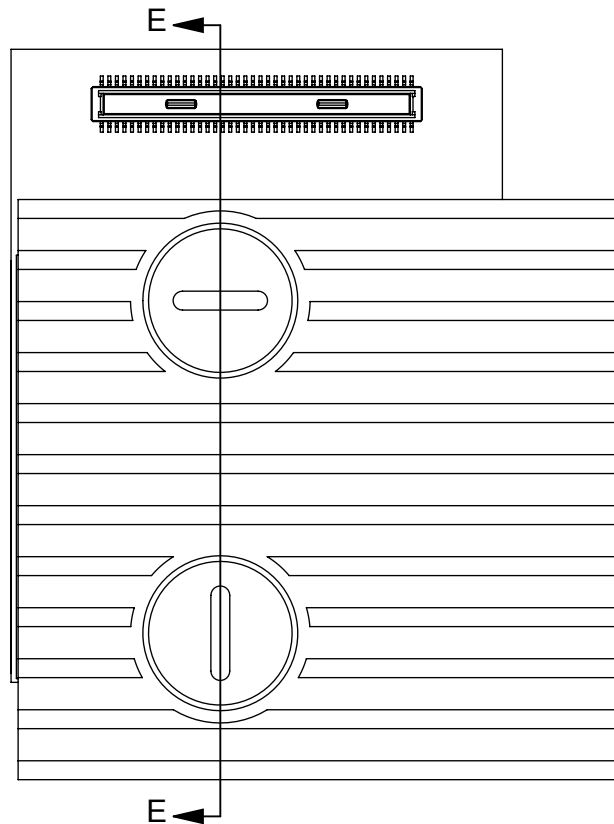
1 THE DMD (ITEM 2) SHOULD BE ALIGNED TO DATUMS 'B' AND 'C' AS SHOWN IN VIEW A. THE FOAM ALIGNMENT SHIMS (ITEM 4) ARE TO BE INSERTED BETWEEN THE DMD EDGES AND THE OPTICAL INTERFACE AT THE APPROXIMATE LOCATIONS SHOWN. THE FUNCTION OF THE SHIMS ARE TO HOLD THE DMD AGAINST DATUMS 'B' AND 'C' AFTER THE DMD HAS BEEN MANUALLY POSITIONED. THIS HOLDS THE DMD IN POSITION WHILE THE REMAINING ASSEMBLY IS COMPLETED

3] WHEN TIGHTENING STANDOFFS (ITEM 8) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOAD FOR THE ELECTRICAL AREA SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE STANDOFFS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREA.

5 WHEN TIGHTENING SCREWS (ITEM 11) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOADS FOR THE THERMAL AREA SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE SCREWS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREA.




VIEW A - DMD ALIGNMENT TO OPTICAL CHASSIS



MOUNTING HOLE SPACING MATCHES TI PROTOTYPE HARDWARE

2	12	LEE SPRING LC 020CD 04M	COIL SPRING	
2	11	2515161	SCREW, SHOULDER	
1	10	2515014	THERMAL PAD	
1	9	2515157	HEAT SINK, SERIES 315 PROTOTYPE	
2	8	2515198	STANDOFF	
1	7	2515158	CLAMP, SERIES 315 PROTOTYPE	
1	6	2515160	INSULATOR, SERIES 315 PROTOTYPE	
1	5	2515159	PCB, OUTLINE SERIES 315, PROTOTYPE	
2	4	2512939	SHIM, FOAM ALIGNMENT	
1	3	2515010	INTERPOSER, 92 CONTACT, HOLE DATUM	
1	2	,	DMD, SERIES 315	
1	1	2515156	INTERFACE, SERIES 315 DMD MOUNTING PROTOTYPE	
QTY	ITEM	PART NUMBER	DESCRIPTION	Notes

BOM Table										
		UNLESS OTHERWISE SPECIFIED <ul style="list-style-type: none">DIMENSIONS ARE IN MILLIMETERSTOLERANCES: ANGLES $\pm 1^\circ$ 2 PLACE DECIMALS ± 0.25 1 PLACE DECIMALS ± 0.50DIMENSIONAL LIMITS APPLY BEFORE PROCESSESINTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994REMOVE ALL BURRS AND SHARP EDGESPARENTHETICAL INFO FOR REF ONLY	DWN J. McKINLEY	DATE 6/19/2016	 TEXAS INSTRUMENTS					
			Engr	ASSEMBLY, SERIES 315 DMD MOUNTING CONCEPT						
			CQE/QA							
			CM							
	0314RD					SIZE B		DWG NO 2515155	REV B	
NEXT ASSY	USED ON	APPLICATION	Apprvd McKINLEY	6/19/2016	SCALE 2:1			SHEET 1 OF 2		

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SSZZ031 January 01, 2013



DWN	DATE
J. McKINLEY	6/19/2016

DATE
6/19/2016

SIZE	B
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DRAWING NO
2515155-Assy-Proto

REV
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SCALE 2:1

SHEET 2 OF 2